

法人說明會

Investor Conference

2025.03.27

GMM



免責聲明 Disclaimer

This presentation contains some forward-looking statements that are subject to substantial risks and uncertainties. Typically, these statements contain words such as “anticipate”, “believe”, “could”, “estimate”, “expect”, “intend”, “plan”, “forecast”, “project”, “predict”, “potential”, “continue”, “may”, “should”, “will”, and “would” or similar words. You should consider these forward-looking statements carefully because such statements are only our expectations or projections about future events, and actual results may differ materially from those expressed or implied by such statements. The forward-looking statements in this presentation include, but are not limited to, growth rates for various markets estimated by third party sources, future products and technology development, widespread market acceptance of the hosted delivery model, future revenue growth and profitability. You should be cautioned that the forward-looking statements are no guarantee of our future performance. The forward-looking statements contained in this presentation are made only as of the date of this presentation and we undertake no obligation to update the forward-looking statements to reflect subsequent events or circumstances, except as required by law.

This presentation and the information contained herein are the property of Gallant Micro. Machining Co., Ltd. Neither this presentation nor any of its contents may be reproduced to a third party without the prior written consent of Gallant Micro. Machining Co., Ltd.



Alliance's Total Market Value: Exceeds **2 Billion** USD

The Alliance Members: 1,500+

R&D personnel: 500+

R&D personnel account for 33%



***c sun* 志聖**

Thermal (熱)
Bonder (壓合)
Lamination (貼膜)
Peeling (撕膜)
UV/Plasma (光/電漿)

GPM 均豪精密

AOI (檢測)
Metrology (量測)
Grinding (研磨)
Polishing (拋光)

GMM 均華精密

Die Attach (黏晶)
Chip Sorter (揀晶)
Auto Jig Saw (切單挑揀)

Alliance Synergy Core Technologies



Company History

- Established in 2010
- 2018 IPO (Stock Code : 6640)

Main Products

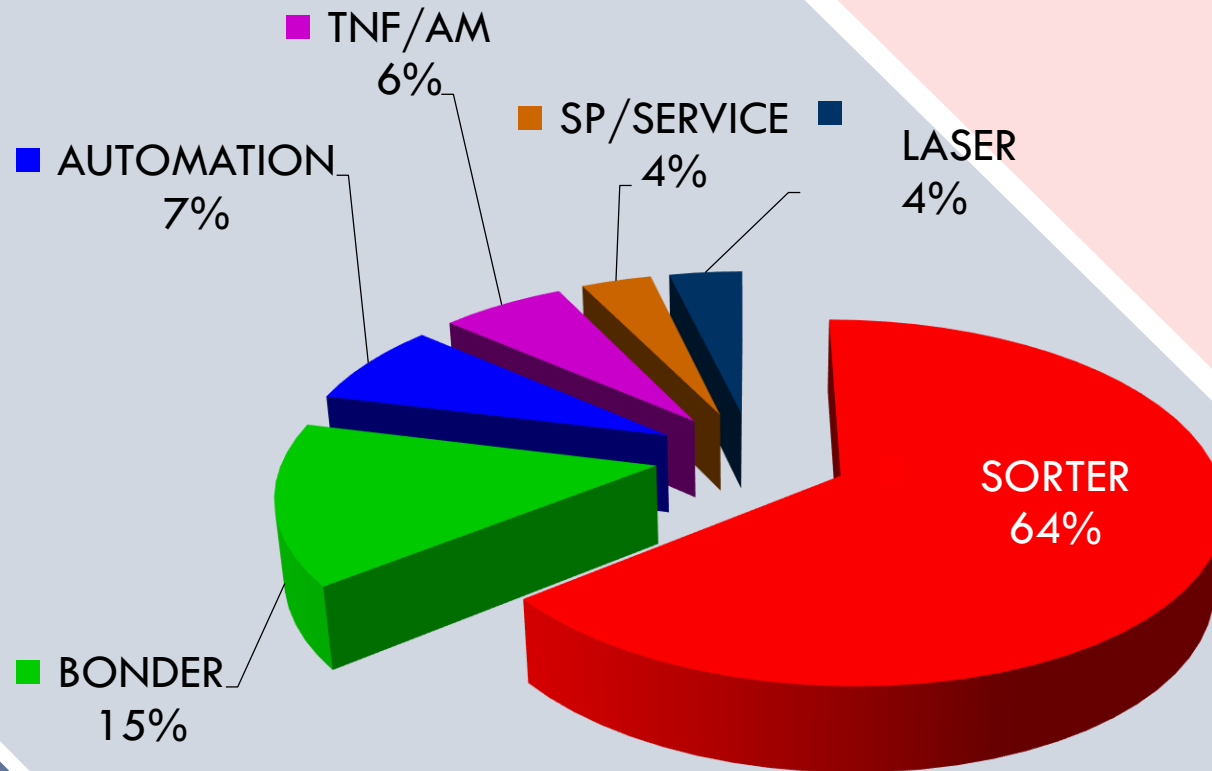
- Advanced Packaging Pick & Place
- Chip Sorter
 - Die Bonder

Business Locations

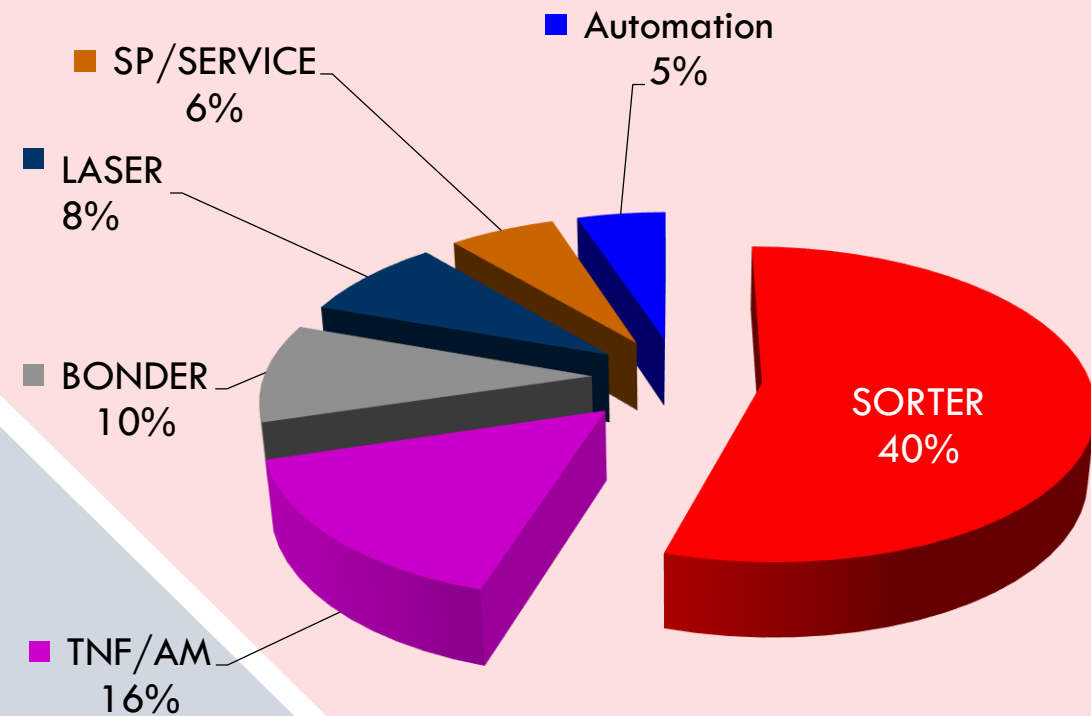
- Tucheng HQ
- Hsinchu
- Suzhou
- Taichung
- Kaohsiung

Product Sales Analysis

2024



2023

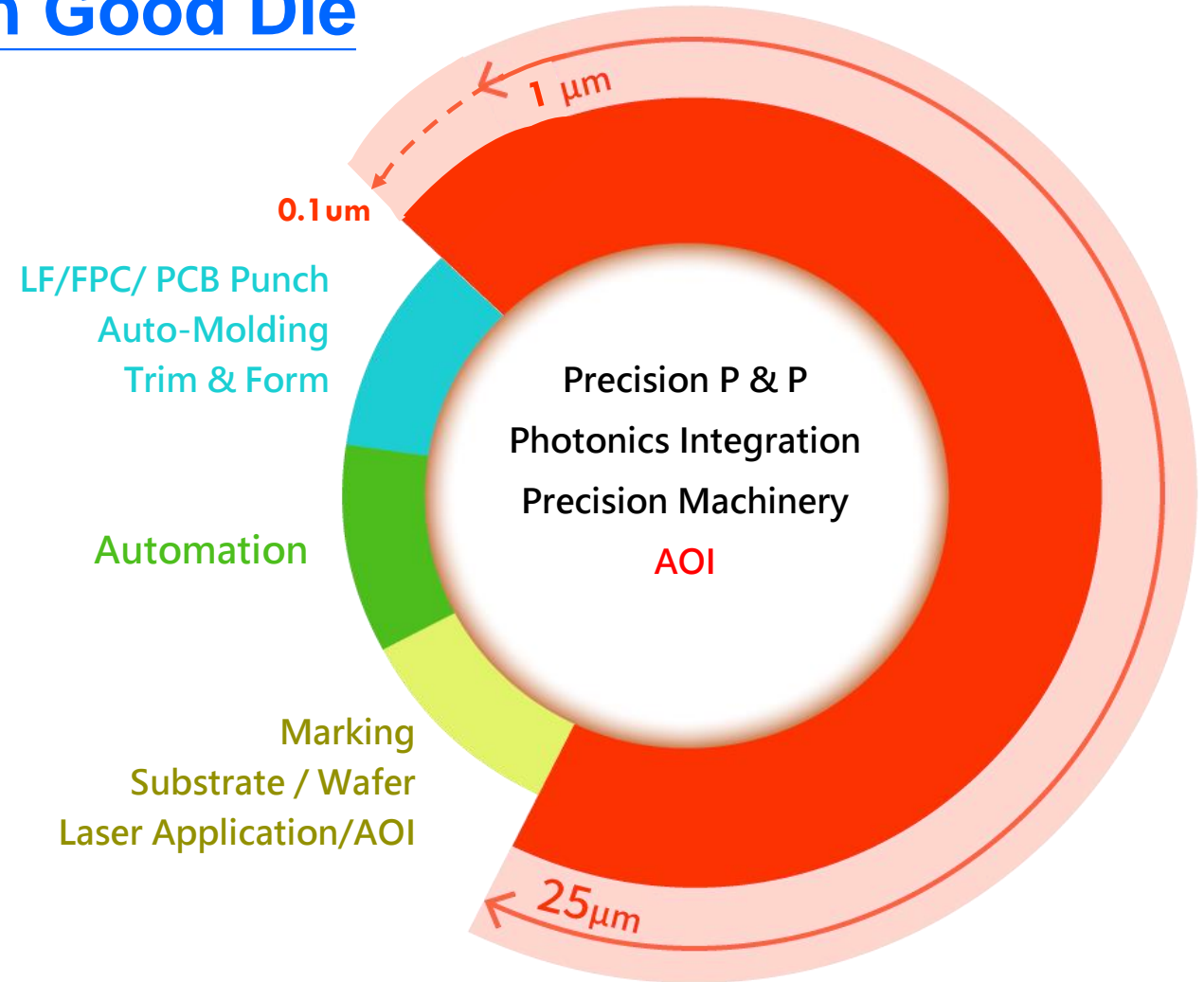


Key Value Technology

GMM

AI Sorter for Known Good Die

6S Inspection Chip Sorter



Die Attach

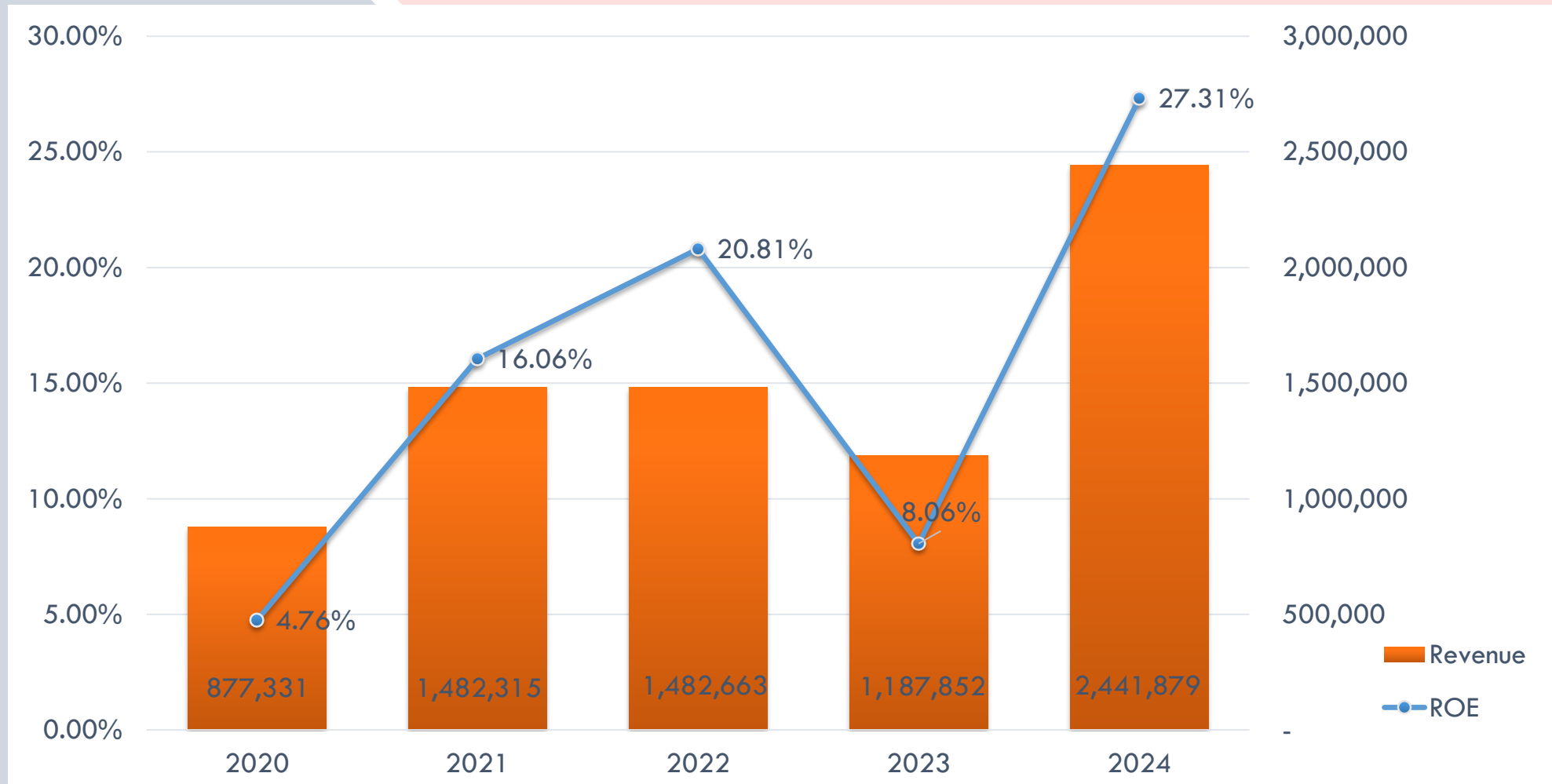
Die Bonder for Fan-out/ InFO/ CoWoS/ FOPLP

Operating Results

Unit: NTD thousands

Year	2024		2023		2022		2021		2020	
Accumulated	Amount	%	Amount	%	Amount	%	Amount	%	Amount	%
Revenue-Consolidated	2,441,879		1,187,852		1,482,663		1,482,315		877,331	
COGS	1,518,370	62.2%	776,443	65.4%	886,296	59.8%	978,554	66.0%	616,404	70.3%
Gross Margin	923,509	37.8%	411,409	34.6%	596,367	40.2%	503,761	34.0%	260,927	29.7%
Operating Expense	481,719	19.7%	292,573	24.6%	350,316	23.6%	342,765	23.1%	276,682	31.5%
Operating Income	441,790	18.1%	118,836	10.0%	246,051	16.6%	160,996	10.9%	- 15,755	-1.8%
Net Income before tax	520,335	21.3%	118,350	10.0%	298,745	20.1%	200,128	13.5%	58,453	6.7%
Net Income after tax	412,772	16.9%	100,857	8.5%	229,720	15.5%	157,506	10.6%	44,522	5.1%
ROE	27.31%		8.06%		20.81%		16.06%		4.76%	
EPS (NT\$/after tax)	\$14.62		\$3.57		\$8.33		\$5.84		\$1.57	
Debt Ratio	55.42%		61.26%		54.09%		59.36%		51.09%	

Revenue & ROE



Operating Results

GMM

Unit: NTD thousands

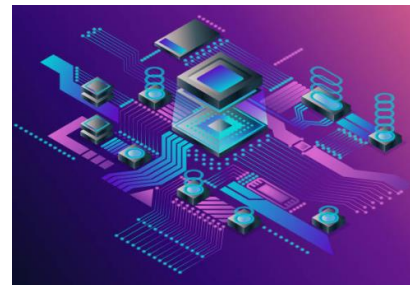
Year	2024	2023	YoY
Revenue-Consolidated	2,441,879	1,187,852	106%
Gross Margin	923,509	411,409	124%
Gross Margin %	37.82%	34.63%	3%
Operating Expense	481,719	292,573	65%
Operating Expense %	19.73%	24.63%	-5%
Operating Income	441,790	118,836	272%
Operating Income %	18.09%	10.00%	8%
Net Income before tax	520,335	118,350	340%
Net Income after tax	412,772	100,857	309%
Net Income after tax %	16.90%	8.49%	8%
EPS (NT\$/after tax)	14.62	3.57	310%

Global Semiconductor Equipment

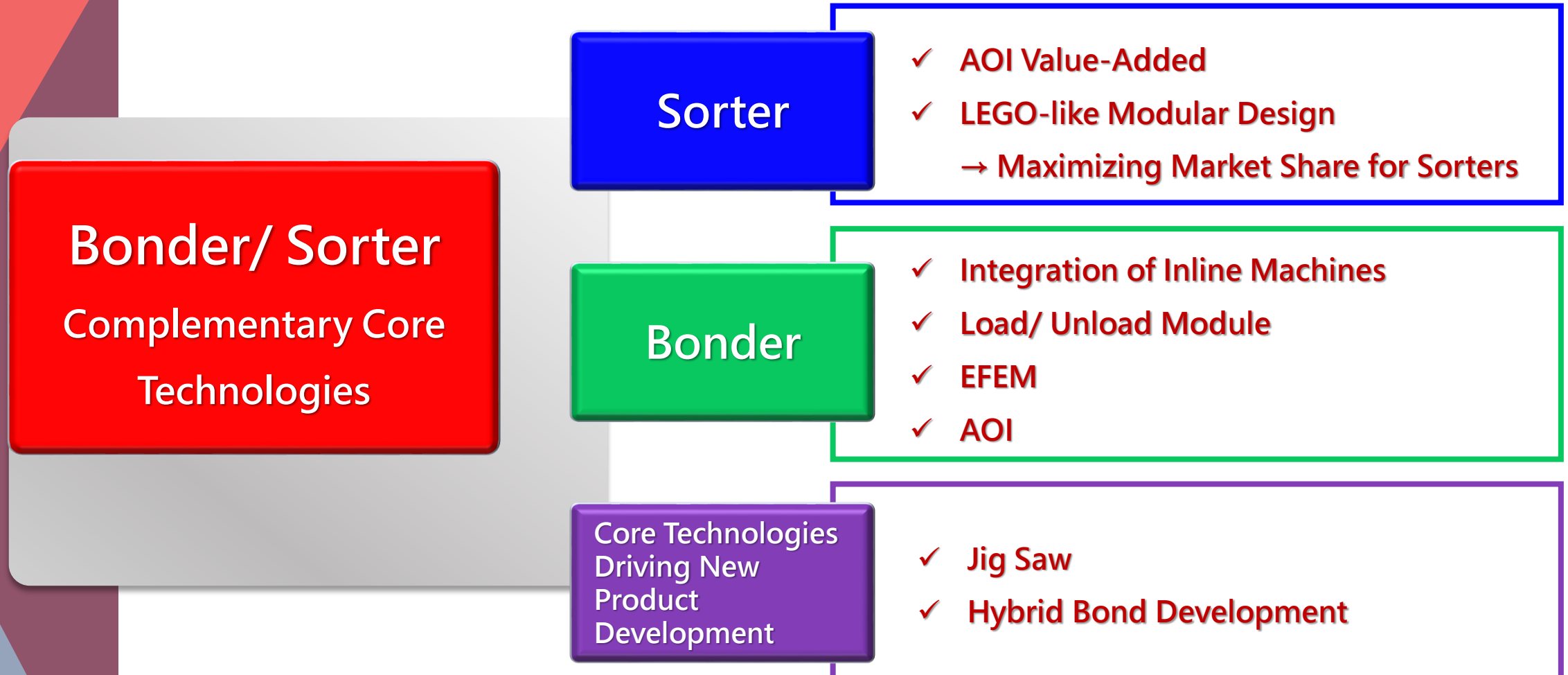
GMM



WSTS ; IEK



Product Development Evolution



2025 Outlook

Based on current business assumptions, Yole Group projects that by 2025, the market share of advanced packaging will exceed that of traditional packaging, reaching 51.03%. The leading foundry and advanced packaging providers anticipate that growing demand for artificial intelligence (AI) and high-performance computing (HPC) will serve as key market growth drivers.

The semiconductor industry continues to exhibit strong growth momentum, with advanced packaging technologies playing a pivotal role in driving industry expansion. As demand for next-generation packaging solutions accelerates, technologies such as Panel Level Packaging (PLP) and Co-Packaged Optics (CPO) are expected to offer significant long-term growth opportunities.

In response to evolving market dynamics, GMM has expanded its R&D engineering workforce by over 30% in 2024 compared to 2023, reinforcing its commitment to technological advancement. Looking ahead, the company expects continued growth in advanced packaging product shipments, with revenue reaching a new record high in 2025.





GMM

G2C+
T STRATEGY ALLIANCE



www.gmmcorp.com.tw

Stock No.
2467.TW
c sun 志聖

6640.TW
GMM 均華

5443.TW
GPM 均豪